



Job: AD9213
Engr: mthiel

Customer: Analog Devices, Inc.
Part No.:
Part Rev:

Stackup & Impedance

Engenix™

Laminate Type Auto
Minimum Tg 170
Min Td 300
MOT 0
PLC Code 0
T260 Min 0
T288 Min 0
Slash Sheet
Laminate Color Natural

Layer	Thickness (Inch)	Stackup Picture	Family	Description	Type
compmask	0.0010		SM-Std	SM-Std	
compside	0.0024		Cu-Std	.5 + Std + C3 Wrap	comp
	0.0050		ISpeed	0.005	
layer2	0.0021		Cu-Std	.5 + Std + C2 Wrap	plane_b
	0.0040		370HR	2116	
layer3	0.0006		Cu-Std	.5	plane_t
	0.0040		370HR	0.0040	
layer4	0.0006		Cu-Std	.5	plane_b
	0.0034		370HR	2113	
layer5	0.0006		Cu-Std	.5	plane_t
	0.0040		370HR	0.0040	
layer6	0.0006		Cu-Std	.5	plane_b
	0.0072		370HR	2113	
			370HR	2113	
layer7	0.0006		Cu-Std	.5	plane_t
	0.0040		370HR	0.0040	
layer8	0.0006		Cu-Std	.5	plane_b
	0.0034		370HR	2113	
layer9	0.0006		Cu-Std	.5	plane_t
	0.0040		370HR	0.0040	
layer10	0.0006		Cu-Std	.5	plane_b
	0.0043	370HR	2116		
layer11	0.0012	Cu-Std	1	plane_t	
	0.0050	ISpeed	0.005		
solderside	0.0021	Cu-Std	.5 + Std + C2 Wrap	solder	
soldermask	0.0010	SM-Std	SM-Std		
0.0628		Total Expected Thickness			
0.0580		After Lamination		+0.0040	-0.0040
Drill/Rout Files:A: plated B: via C: plated-X2					

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




Requirements Information in Inches

Top Layer	Bottom Layer	Required Thickness	Tol +	Tol -	Calculated Thickness
Incl.Plating		0.0620	0.0060	0.0060	0.0608
After Lamination		0.0580	0.0040	0.0040	0.0575

Comments

Concise Impedance Constraint Information

Line Widths in Inches

#	Impedance Type	Aff Layer	Designed Width	Edited Width	Cntr to Cntr	Spacing	Ref Planes	Target ohms	Predicted ohms
1	Surface MS 	compside	0.026	0.026			None layer2	25 +/- 2.5	24.95
2	Surface MS 	compside	0.0085	0.0085			None layer2	50 +/- 5.0	49.51
3	EC Microstrip 	compside	0.021	0.021	0.027	0.006	None layer2	50 +/- 5.0	49.91
4	EC Microstrip 	compside	0.005	0.005	0.011	0.006	None layer2	100 +/- 10.0	98.92
5	EC Microstrip 	compside	0.007	0.007	0.02	0.013	None layer2	100 +/- 10.0	100.09
6	Surface MS 	solderside	0.0085	0.0085			None layer11	50 +/- 5.0	49.78
7	EC Microstrip 	solderside	0.005	0.005	0.011	0.006	None layer11	100 +/- 10.0	100.46
8	EC Microstrip 	solderside	0.007	0.007	0.02	0.013	None layer11	100 +/- 10.0	101.06